

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	12.0	+3.0/-12.0	PLATED	1107
A	63.0	+3.0/-3.0	PLATED	11
△	60.2	+2.0/-2.0	NON-PLATED	9
+	78.7	+2.0/-2.0	NON-PLATED	1
○	146.0	+3.0/-3.0	NON-PLATED	4
+	189.0	+3.0/-3.0	NON-PLATED	4

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010". DIMENSIONS ARE FOR REFERENCE ONLY. USE ARTWORK FOR ACCURATE MEASUREMENT OF THE BOARD OUTLINE.
- THE PWB SHALL BE FABRICATED TO IPC-6011 AND IPC-6012, CLASS 2, TYPE 3. WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT. RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
- BOARD MATERIAL & CONSTRUCTION TO BE U.L. APPROVED AND MARKED ON THE FINISHED BOARD. ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS. PCB MUST BEAR THE UL94-0 REGISTERED MATERIAL ID NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- .010" AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- INNER PLANE LAYERS TO BE 1/2 OZ. COPPER. INNER SIGNAL LAYERS TO BE 1/2 OZ. COPPER. OUTER LAYERS TO BE 1/2 OZ. COPPER + PLATING.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- ALL HOLES ARE ON A 0.0001 GRID EXCEPT THOSE INDICATED.
- MAXIMUM RATED VOLTAGE BETWEEN CONDUCTORS SHALL BE 65 VOLTS PEAK.
- NO BREAKOUT ALLOWED ON PLATED THROUGH HOLES.
- FOIL OUTER OPTIONAL.
- INTERPRET DIMENSIONS IN ACCORDANCE WITH ASME Y14.5M-1994.
- TEARDROP VIAS AS NECESSARY.
- THIEVING IS NOT ALLOWED.

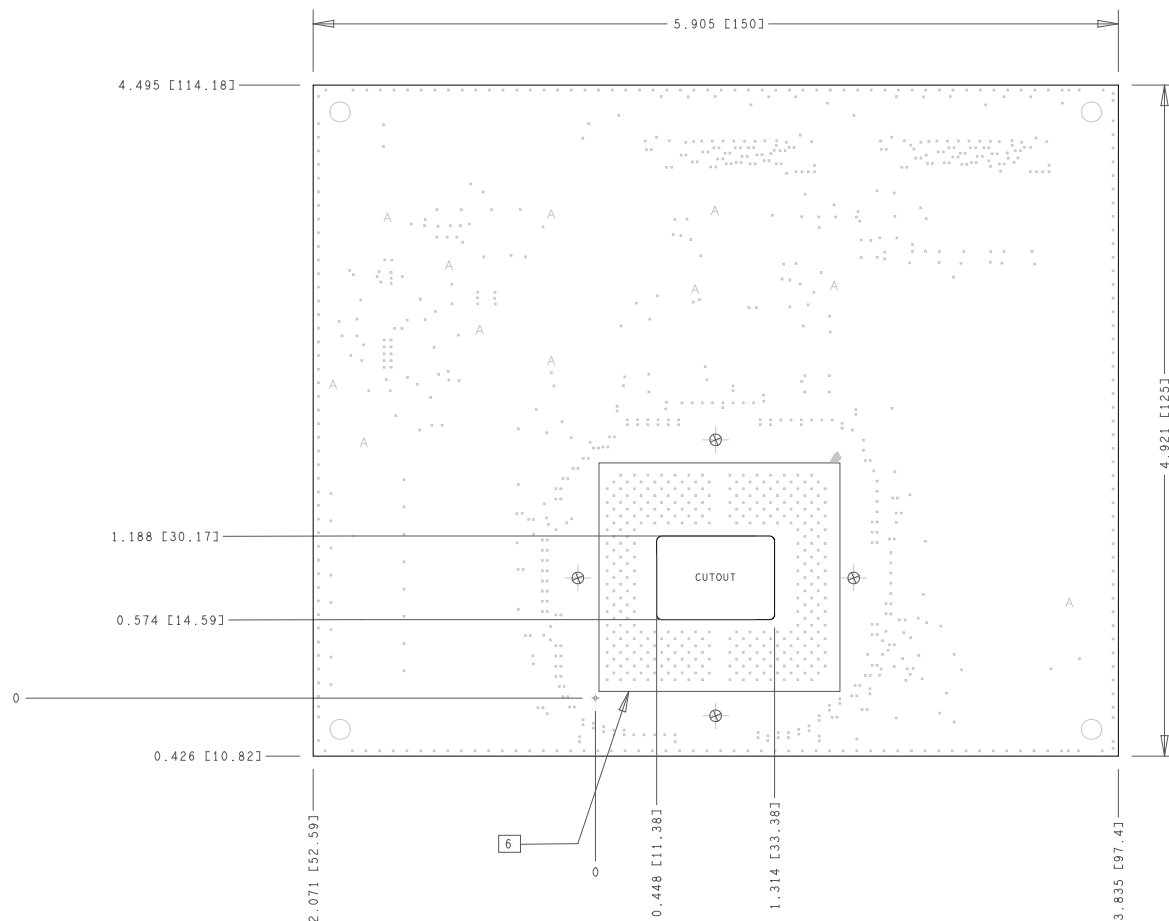
PROCESS NOTES:

- EXCEPT AS NOTED BELOW, ALL EXPOSED CONDUCTORS ON BOTH SIDES PWB SHALL BE ELECTROPLATED GOLD (5-15 MICROINCHES) OVER ELECTROPLATED NICKEL (50 MIN MICROINCHES).

- APPLY LPI SOLDERMASK. COLOR: RED. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H, CURRENT REV.
- FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT BOTH SIDES PER THE ARTWORK. COLOR: WHITE.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- PLATE INDICATED PAD AREAS WITH A MINIMUM OF 30. MAXIMUM OF 50 MICROINCHES ELECTROLYTIC HARD GOLD OVER A MINIMUM OF 50 MICROINCHES OF ELECTROLYTIC NICKEL.

CONTROLLED IMPEDANCE

LAYER STACKUP	50 OHMS SINGLE ENDED +/-10%	WIDTH/SPACING 100 OHMS DIFFERENTIAL +/-10%
LAYER 1 - PRIMARY SIDE/GND FILL		
LAYER 2 - SIGNAL	0.0057"	0.0048/0.0074
LAYER 3 - GND PLANE		
LAYER 4 - SIGNAL	0.0065	0.0050/0.0072
LAYER 5 - GND PLANE		
LAYER 6 - SIGNAL	0.0047"	0.0042/0.0080
LAYER 7 - GND PLANE		
LAYER 8 - SECONDARY SIDE/PWR FILL		



TEXAS INSTRUMENTS			
BOARD NAME:	0.98 HSSI DMD BOARD	DESCRIPTION:	FAB DRAWING
PROJECT #:	DLP-30179-02	DATE:	12 NOV 2018
		REVISION:	